

# **Chipboard handbook**





# **Koskisen Chipboard Handbook**

The Koskisen company was founded in 1909. Koskisen is known as a manufacturer of mechanical forest industry products. Koskisen is the only chipboard manufacturer in Finland, with a capacity of around 100,000  $\mathrm{m}^3$ .

# **1. General**

<span id="page-1-0"></span>**KOSKISEN** 

The raw materials of chipboard are by-products of sawn timber and plywood production. The sawdust and birch veneer woodchips come directly from the sawmill and plywood production line on the same property. Logs come from within a radius of approximately 100 km of Järvelä and are certified timber. Recycled materials are not used in the chipboard, as enough by-products are used and the result is a pure, light board.

The chipboard is made by compressing wood shavings and resin. In chipboard made by hot pressing, the chips generally run in the direction of the surface. Both sides of the surface of the board are sprinkled with very fine wood particles, while the coarser chips are on the inside. The chips of the surface layer are smaller and thinner than those in the middle layer, meaning the surface of the chipboard is compacter and denser than the centre of the board. The production line can manufacture several different quality grades that are optimised for the intended application.

# **2. Chipboard use**

In terms of its basic properties, chipboard is comparable to timber. In addition, the manufacturing method gives it certain advantages, such as no grain pattern, homogeneity and constancy of strength in every direction along the plane of the board. In addition, linear dimensional changes are minimal (Puuinfo pages).

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# 2.1 Chipboard applications

Chipboard is generally used in construction, such as in walls and floors, and in furniture, such as cabinets and kitchen fixtures. Chipboard can be manufactured in an almost continuous range of thicknesses from 3 to 50 mm, with various strengths. The chipboard strength grade is chosen according to the intended application.

It is important to choose the right type of board for the right application. The list below shows examples of suitable strength grades according to application.

- In terms of its basic
- properties, chipboard is comparable to wood.
- *In the manufacturing process of our quality chipboard, we utilise the raw material side*
- *streams generated in our own units' production.* **5**



# We make full use of each log





TABLES

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THERMAL<br>PROPERTIES





P6 Flooring panels

**P7** Heavy duty

The applications for chipboard are indoor and covered spaces. P5 chipboard contains resin which makes it slightly more moisture-resistant, but it is not intended

for actual outdoor use.

Wet room fixtures may be exposed to a very wide range of moisture conditions depending on the presence of a sauna and the exposure of the fixtures to splashes, for

example.

It is important to choose  $\cdot$  the right type of panel for the right application.

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Generally, "wet room" means a room in which the floor surface is exposed to water and in which water may splash or condense on the wall surfaces (e.g., bathroom, shower room, sauna). Chipboard should not be used in the structures of wet rooms in which water is continually used, such as shower rooms. Floors and walls that are exposed to splashing water must always be built strictly watertight to prevent water damaging the structures.

(RT card, 2007)

Chipboard with better moisture capacity than standard chipboard is intended for use in RIL 120-compliant moisture class 2. P2Mr and P5-class boards, which are coated with melamine film at the factory, are also suitable as

interior wall cladding boards.

2.2 Chipboard use conditions

Chipboard is intended for use in dry spaces. Table 1 presents moisture classes in accordance with RIL 120 (RIL

THERMAL<br>PROPERTIES

Class Name Monthly average of relati-

Table 1. Service moisture classes in accordance with RIL 120.

# 2.3 Chipboard moisture

Upon delivery, chipboard has a moisture content of 3–7%. Storage moisture conditions affect the moisture content of the chipboard as per table 2:

Table 2. Relative air humidity % +20°C.

Chipboard equilibrium moisture content at various air humidity levels.

ve humidity RH

 $0.8 \leq R$ H < 0.95

3 protected from wetting

4 exposed to wetting 0.95 ≤ RH

1 indoor, dry RH < 0.6 2 outdoor, dry  $0.6 \leq RH \leq 0.8$ 



# **Swelling and** shrinkage **of board as a function of relative air humidity**



Figure 1. Changes to dimensions of the board as a function of air humidity.

TABLES

 $120 - 2004$ ).



**3. Technical properties of Koskisen chipboard** 

# 3.1 Board dimensions

The dimensions of the chipboard production line enable the manufacture of specific board dimensions. Table 3 presents standard dimensions.

# 3.2 Tolerances

The tolerances of chipboard dimensions are presented in tables 4 and 5.

# 3.3 Chipboard surface qualities

Quality A is generally used as a painted and melamine-coated board and quality B is suitable for purposes such as laminating.



\* Edge-banding sizes: Max. 1200 x 2750 mm edge-banding of two sides. Max. edge-banding of four sides 1200 x 2500 mm. Minimum size 220 x 220 mm



Basic board

 $15$ 



Table 4. Chipboard tolerances by factory and standard

Table 3. Standard chipboard dimensions.

### Table 5. Straightness and squareness tolerances of chipboard.



SIGN<br>BLES

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 $\bullet$ 

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- PLASIGN EMISSIONS<br>[- FLOORS](#page-5-0) EMISSIONS

# **4. Chipboard strength grades**

Chipboard is classified based on bending strength and humidity swelling requirements. The higher the grade, the higher the strength and the more demanding the application requiring a durable, high-strength board.

Table 8 presents the grades and the requirements set for them in accordance with EN 312. Chipboards which are intended for use in construction: properties and conformity to requirements are defined in standard SFS – EN 13986 + A1.

Table 7 presents the target densities of Koskisen chipboard in various strength classes, and the tolerance is +/- 10%







# **Modulus of elasticity in bending N/mm2 (EN 310)**

Table 8. Summary of chipboard standard requirements EN 312:2010

# **Bending strength N/mm2 (EN 310) Internal bond tensile strength N/mm2 (EN 319)**









**Swelling in thickness after humidity/moisture stress test % (EN 321)**

# **Swelling in thickness after 24 h immersion in water % (EN 317)**

Table 7. Koskisen chipboard target densities in various strength grades.

## **Internal bond tensile strength after moisture stress test N/mm2 (EN 321)**

<span id="page-4-0"></span>

Our website shows standard coatings and colour models. Melamine-coated furniture board is sold under the KoskiMel product name.

Tailored special boards are manufactured under the KoskiPro product name. Its properties, such as weight, are defined by client requirements. KoskiPro can be coated with various coatings such as melamine, phenol coating and glued coatings.

# **5. Coatings and specialty products**

Chipboard can be coated with several different coatings, including hot pressed melamine or phenol film. A wide range of patterns is available. Laminates and plastic coatings may also be glued to the chipboard surface. The coating is chosen in accordance with the application and customer requirements.

In Zero furniture board, the fossil binder has been replaced with a renewably sourced wood-derived binder, lignin. Thanks to its versatility and durability, Zero is perfectly suited to the needs of the furniture industry. It is also available coated with melamine f ilms.

# **6. Design – Floors**

To assist the design of floorboards, mathematical values have been calculated as an aid for chipboard strength grades P5 and P6. The bases for calculation are presented here. The values are simulated and indicative. In addition, local guidelines and building codes must be taken into considertion.

The density and moisture content of the chipboard, as well as the duration of the load, affect its strength values. Thinner boards are generally stronger than thick ones as they have a higher relative proportion of dense surface layer than thick boards. Because the chipboard strength values presented in table 4 are determined on the basis of short-term static trials, they cannot be used as such as a basis for design. The characteristic strengths and moduli of elasticity to be used in measuring load-bearing structures are presented in the SFS EN 12369-1 Wood-based Panels publication. Characteristic structural design values. Part 1.

# 6.1 Uniformly distributed load

An uniformly distributed load affects the entire support span consistently. The length of the board is taken to be infinite in one direction and as long as support span L in the other. Thus, the case of uniformly distributed load may be simplified to beam theory, from which the infinite side of the board is omitted from the calculations.

# **6.1.1 Deflection, single-span**

The deflection of a single-span beam may be obtained with beam theory. For an evenly loaded beam, the largest deflection is located in the middle of the beam and may be defined according to formula 1:

# **6.1.2 Deflection, double span**

For a double span beam with an uniformly distributed load, the maximum value of the deflection for the beam is obtained with formula 2:

Thus, the deflections of a double span case may be obtained from the single-span deflection tables by multiplying them by the number:

$$
\frac{V_{\text{max. single span}}}{V_{\text{max. double span}}} = \frac{384}{925}
$$





$$
V_{\text{max. 1-span}} = \frac{5qL^4}{384El} = \frac{5q_{\text{surface}}bL^4}{384E^{\frac{b^e}{12}}} = \frac{5q_{\text{surface}}L^4}{32Et^3}
$$

 $q<sub>surface</sub> = surfaceload = span$ 

 $E =$  average module of elasticity t = thickness

$$
V_{\text{max. 2-span}} = \frac{qL^4}{185EI} = \frac{q_{\text{surface}}bL^{\text{up}}_{12}}{185E} = \frac{12q_{\text{surface}}L^4}{185Et^3}
$$

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## **6.2.2 Capacity double span**

In a double span case, the maximum moment remains the same as with a single span, meaning the capacity with regard to the bending is the same as on a single-span supported beam. The maximum moment appears at the central support.

Shear strength may be proven through shear stress and bending strength. When shear strength is calculated, the curved shape of the structure is considered, in which case, per standard EN 1995-1-1, the value of 2/3 is used in the way shown in section 6.1.7(2) as the plate's effective width. As a result, formula 7 is obtained:

In a double span case, with thick material strengths and short support spans, the shear strength may become dominant. In practice, with uniformly distributed load, this occurs in both P5 and P6 boards with the thickest material strength used in the calculations t = 38 mm together with the shortest support span L = 300 mm.

The greatest shear force in an evenly loaded double span beam is on the central support of the beam, and its value is obtained with formula 6:

When determining the capacity of an uniformly loaded double span beam, the smaller of the values obtained from formulas (5) and (7) is used.

Where in this case  $x = u = L/2$  and y=0. In this case, the deflection caused by the load at the centre of the support span at the site of the load is per formula 9:

# 6.2 Capacity

## **6.2.1 Capacity single-span**

The strength of a single-span beam with an uniformly distributed load may also be obtained directly with beam theory. Bending strength is considered a dominant case. The maximum moment for a single-span beam with an uniformly distributed load is obtained with formula 3:

The bending strength is in accordance with formula 4:

And when the board's bending strength is known, the permitted strength is obtained in accordance with formula 5:

On a single-span beam, the shear strength does not become dominant.

# 6.3. Point load

The result of the sum  $\sum_{n=1}^{\infty} \frac{1}{n^3}$  is an Apéry constant, which is approximately 1.2025. Correspondingly, the result of the sum  $\sum_{n=1}^{\infty} \frac{1}{(2n)^3}$  is 1/8 of an Apéry constant, in which case the value of the deflection may be written in its final form with formula 10: ∞ n=1

The point load is assumed to affect the centre of the support spans. The length of the board is taken to be infinite in one direction and as long as support span L in the other.

### **6.3.1 Deflection with point load – single-span**

The deflection of a single-span beam can be derived from levykenttä teoria. For a simply supported, on opposing sides, infinite plate strip the deflection equation (formula 8) is in valid:

Depending on parameter n, the value of the product of the sine phrases is either 0 (even n) or 1 (odd n). Thus, an equation may be formed:

In other words, the sum of even numbers is subtracted from the sum of all positive integers, as the sine function multiplying the sum by an even n returns the value 0.











$$
v(x,y) = \frac{Fa^{2}}{2\pi^{3}D} \sum_{n=1}^{\infty} \frac{1}{n^{3}} \sin(\alpha_{n}u) \sin(\alpha_{n}x) [ (1 + \alpha_{n}y)e^{-\alpha_{n}y} ]
$$
  
where  $D = \frac{Eh^{3}}{12(1-v^{2})}$  and  $\alpha_{n} = \frac{\pi}{L}$ 



$$
V_{\text{max}} = V(\frac{L}{2}, 0) = \frac{Fa^{2}}{2\pi^{3}D} \sum_{n=1}^{\infty} \frac{1}{n^{3}} \sin(n \frac{\pi}{2}) \sin(n \frac{\pi}{2})
$$

$$
V_{\text{max}} = V(\frac{L}{2}, 0) = \frac{Fa^{2}}{2\pi^{3}D} \sum_{n=1}^{\infty} \frac{1}{n^{3}} - \sum_{n=1}^{\infty} \frac{1}{(2n)^{3}}
$$

$$
V_{\text{max}} = V(\frac{L}{2}, 0) = \frac{Fa^{2}}{2\pi^{3}D} (\frac{7}{8} \times 1.2025) = \frac{6FL^{2}(1-v^{2})}{\pi^{3}Et^{3}} (\frac{7}{8} \times 1.2025)
$$

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# **6.3.3 Capacity – double span**

The point load capacity of a multi-span plate may be calculated using formula 17 for bending:

, in which α may be expressed with sufficient precision for 300 mm – 1200 mm support span using formula 18, when the width of the point load is 50 mm.

By tabling b's values for various support span lengths, it is observed that width of the equivalent depends in linear fashion on the length of the support span. Equivalent width may be evaluated with reasonably accuracy using formula 16:

Now the capacity tables may be formed using the beam-theory-compliant formula 13 by using the defined equivalent width per formula 16.

### **6.3.2 Deflection, double span**

The deflection of a double span plate is not analytically easy to solve. Thus, the calculation makes use of the RFEM element calculation software, which is used to define the double span plate's relative deflection compared to a single-span one. To obtain a valid result, two plates are modelled as both single- and double span:

• Support span 500 mm, long side 10 m, load at the centre of the plate

• Support span 1200 mm, long side 10 m, load at the centre of the plate

In both cases we note that the ratio of the maximum values of the deflection between the single- and two-span plate is 0.599..; that is, it remains stable notwithstanding the support span.

Capacity is defined by beam theory in which the equivalent width, which is defined as the input data on the basis of VTT-provided table data capacity results, serves as the width of the diaphragm. The functionality of the width equivalence, that is, the correspondence of the bending stresses formed by it on point load and the board, are proven with the ANSYS calculation software.

$$
V_{\text{max. 2-span}} =
$$
  
 
$$
V(\frac{L}{2}, 0) = 0.6 * \frac{Fa^{2}}{2\pi^{3}D}(\frac{7}{8} * 1.2025) = \frac{3}{5} \frac{6FL^{2}(1-v^{2})}{\pi^{3}Et^{3}}(\frac{7}{8} * 1.2025)
$$

For a single-span beam with a point load at the centre, the maximum moment is calculated using formula 12:

And the bending stress is calculated with formula 13:

, in which the defined equivalent width beqv must be used as width b. The point load capacity is obtained once the board's bending strength has been defined by solving the strength in formula 12 and replacing bending stress with bending strength, as a result of which formula 14 is obtained:

The equivalent width is calculated backwards with input data from the obtained tables so that the support span length L and point load capacity F are known, after which the equivalent width b in formula 15 is solved:



$$
F = \frac{2b_{\text{eq}v}f_t^{t^2}}{3L}
$$



$$
b_{\text{eqv}} = \frac{16}{25} L + 140 \text{ mm}
$$

$$
\sigma_t = \frac{M_{max}}{I} \ y = \frac{\binom{F_L}{4}}{\binom{\frac{b^p}{12}}{12}} \ \frac{t}{2} \ = \ \frac{3FL}{2bt^2}
$$

$$
F = \frac{f_t^{t^2}}{6\alpha}
$$







6.4 Combination factors in accordance with service and duration classes

The conditions of the application must also be taken into account when using design values.

### **6.4.1 Deflections**

The service class (humidity conditions) and load duration class are taken into account by increasing the deflections defined in chapters 1.1 and 1.2 using the factors in standard SFS EN 1995-1-1. In the case of a deflection, the deflection should be increased by the factor in accordance with formula 21:

 $k$  deflection  $(1+k_{def}\Psi_2)$ 

, where  $k_{\text{def}}$  is defined in table 3.2 of standard SFS EN 1995-1-1. Eurocode does not take a position on the load duration classes regarding deflections. Rather, it classifies them in accordance with primary load cases (e.g., snow load, payload, permanent load). Thus, factor, is defined in reverse with input data from the report provided\*, in which case the results remain comparable for added material strengths.

In a double span case, with thick material strengths and short support spans, the shear

For factor  $k_{\text{def}}$  the values of P5 chipboard are used, because kmod factors are not defined for P6 board in the standard for all service classes. This is a conservative assumption.

strength may become dominant. In practice, with point load, that occurs in both P5 and P6 boards with the thickest material strength used in the calculations t = 38 mm as well as with the shortest support span  $L = 300$ mm, as well as in P5 board with the thickest material strength and a support span of L = 350 mm.

> , where  $k_{mod}$  is defined in table 3.1 of standard SFS EN 1995-1-1.

> > : The conditions of the end use

The greatest shearing force in a locally loaded plate is a local point load F (formula 19)

### $V_{\text{max}} = F$

For factor  $k_{mod}$  the values of P5 chipboard are used, because kmod factors are not defined for P6 board in the standard for all service classes. This is a conservative assumption. In addition, comparability with the reference tables provided as input data is retained\*



Shearing durability may be proven through shearing stress and shearing strength. For a locally stressed plate with loading width c (50 mm), formula 20 is obtained for point load durability via shearing stress:

> : must also be taken into account when using design values.

When determining the capacity of a point loaded double span beam, the smaller of the values obtained from formulas (17) and (20) is used.

$$
T = \frac{F}{4ct} \longrightarrow F_{shear.capacity.2-span} \qquad = 4cf_v t
$$





### **6.4.2. Capacity**

The service class (humidity conditions) and load duration class are taken into account by reducing the deflections defined in chapters 1.1 and 1.2 using the  $k_{\text{mod}}$  factor in standard SFS EN 1995-1-1. In addition, the material's partial safety  $Y_M = 1.3$  and the load's partial safety  $Y_q =$ 1.5 are taken into account. In the case of durability, the capacity must be reduced by the factor in formula 22:









# **7. Design tables P5 board**







Table 8: Deflection, constant load q=1 kN/m2, P5, single span

Table 9: Deflection, constant load q=1 kN/m2, P5, double span

The deflections needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values:







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The capacities needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values of the classes (incl.  $\gamma_M$  = 1.3 and  $\gamma_q$  = 1.5):





### Table 10: Specific capacity, constant load kN/m2 single span P5

### Table 11: Specific capacity, constant load kN/m2 douple span P5

**P5 board**















### Table 12: Deflection, concentrated load in the centre of a support span F=1 kN, P5, c=50 mm, single span

### Table 13: Deflection, concentrated load in the centre of a support span F=1 kN, P5, c=50 mm, douple span

The deflections needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values:

# **P5 board**











The capacities needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values of the classes (incl.  $\bm{{\mathsf{y}}}_{\mathsf{M}}$ = 1.3 and  $\bm{{\mathsf{y}}}_{\mathsf{q}}$  = 1.5):





### Table 14: Specific capacity, concentrated load in the centre of a support span, kN, P5, c=50 mm, single span

### Table 15: Deflection, concentrated load in the centre of a support span F=1 kN P5, c=50 mm, douple span

# **P5 board**















### Table 16: Deflection, constant load 1 kN/m2, single span P6

### Table 17: Specific capacity, constant load kN/m2 douple span P5

The deflections needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values:











The capacities needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values of the classes (incl.  $\gamma_M$  = 1.3 and  $\gamma_q$  = 1.5):





### Table 18: Specific capacity, constant load kN/m2 single span P6

### Table 19: Specific capacity, constant load kN/m2 douple span P6















### Table 20: Deflection, concentrated load in the centre of a support span, F= 1 kN, P6, c=50 mm, single span

### Table 21: Deflection, concentrated load in the centre of a support span, F=1 kN, P6, c=50 mm, douple span

The deflections needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values:











The capacities needed in various load service and duration classes are obtained by multiplying the values in the table above by the following values of the classes (incl.  $\gamma_M$  = 1.3 and  $\gamma_q$  = 1.5):





### Table 22: Specific capacity, concentrated load in the centre of a support span, kN, P6, c=50 mm, single span

Table 23: Specific capacity, concentrated load in the centre of a support span, kN, P5, c=50 mm, douple span









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# **8. Emissions**

# 8.1 Gluing of chipboard

Urea formaldehyde resin is primarily used as the glue in standard chipboard. The amount of resin in chipboard at the manufacturing stage is approximately 10%. The formaldehyde contained in the resin is for the most part released during hot pressing, but a portion of it remains in the product and is released over time. The amount of formaldehyde in a wood-based board is an important criteria when choosing boards for various applications, and different markets require products of different emission classes. For example, the US and Japanese markets have traditionally required very low formaldehyde emissions.



# 8.2 Formaldehyde and emissions

The formaldehyde emission of the finished product is monitored regularly in quality control, for which several test methods and class limits exist. Factory quality control uses an extraction method known was perforation (EN 120; EN 12460-5) by which the amount of formaldehyde is obtained as a unit mg/100 g sample. The amount is reduced to 6.5% constant humidity in a sample piece.

The chipboard is CE marked and conform to the corresponding E1 emissions class whose limit value is 8 mg/100 g sample (SFS-EN 13986 + A1 Wood-based panels for use in construction. Characteristics, evaluation of conformity and marking). In practice, E1-class chipboard has significantly lower values than 8 mg/100 g sample. For comparison, natural wood has been measured and produced corresponding values of 3…10 mg/100 g.

Chipboard formaldehyde emissions may also be reduced by coating or painting the boards.

There are also products in production with lower formaldehyde emissions than the E1 level. So-called E05 means half the E1 limit or 4 mg/100g. This has yet to be standardised, nor has the official CE mark-compliant emission yet been confirmed.

# 8.3 M1 indoor air classification

Choice of materials can be used to affect the quality of buildings' indoor air. The M1 emissions classification label of building materials is a sign of low emissions. The M1 classification sets limit values for materials' and fixtures' total volatile organic compounds (TVOC) and formaldehyde and ammoniac emissions. In addition, the product's odour is evaluated.

The KoskiLam product is classified M1.

# 8.4 Eco-labels

The Nordic Swan Ecolabel is a type 1 environmental label regulated by the ISO 14024 standard. The label is voluntary, sets a wide range of environmental requirements for the product or service and is based on life cycle thinking.

Currently, four products from the chipboard factory's selection have the Nordic Swan Ecolabel:

– KoskiMel E0.5 – KoskiPan E0.5 – ZeroMel – ZeroPan



Table 24. Formaldehyde measurement method in wood-based boards.



\*\*) not in strength grades P5 and P7

In addition, the product range includes TSCA-certified chipboard, the emission content of which has been certified by the US Environmental Protection Agency (EPA) in accordance with the Toxic Substances Control Act (TSCA) Title VI. ULEF status has been obtained for chipboard of this emission level, in which case the product's formaldehyde emission is below 0.05 ppm. This chipboard has the lowest formaldehyde emissions of all.

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Table 24 presents the measurement methods and limit values of emissions.

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# **9. Thermal properties of chipboard**

9.1 Thermal properties

**9.1.1 Thermal insulation** The thermal insulation of chipboard depends on its humidity

λ10 = 0.13 W/mK λn = 0.14 W/mK (SRakMK/C4)

**9.1.2 Vapour permeance** 3…7 x 10-12 kg / msPa (Dick Björkholz: Heat and humidity)

**9.1.3 Air permeability** 10…25 x 10-9 m² / sPa (RT 22-10517)

# **10. Fire class**

In conformity with the CE label, chipboard which is used in walls and ceilings is in fire class D-s2,d0 if its density is above 400 kg/m<sup>3</sup> and thickness is above 9 mm. Koskisen does not use fire retardants which could improve fire properties in chipboard.

Uncoated chipboard with the same criteria (CE label) (density 400 kg/m3 and thickness above 9 mm) floor chipboard conforms to Dfl-s0 class in accordance with EN 13501.

Melamine or phenol-coated chipboard for floors conforms to Bfl-s1 fire class in thicknesses 12–38 mm (EN 13501-1).

Wood-based board chars at a rate of approximately 1 mm/min.

# **11. Sound insulation**

The sound insulation of 12–18 mm chipboards is 24–29 dB. Chipboard can be used as a vibrating surface for the dampening of low noise as well as part of other sound dampening structures. Sound dampening capability can be improved through perforating and grooving. Table 25 presents the measured sound reduction values of chipboard.



Table 25. Measured sound reduction values, airborne sound reduction figure per Rw ISO 717-1:2013.

Mineral wool between the boards improves the structures sound insulation by 5–8 dB. The best sound insulation is achieved with a double frame structure. If for board cladding

sufficiently thick and heavy chipboard or two boards one on top of the other combined with mineral wool insulation is used, the airborne sound insulation can be improved up to 55…60 dB.

Table 26 presents values for various combined structures' airborne sound insulation. (RT R-3729







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# **12. Installation instructions**

# 12.1 Floors

The links below are to installation instructions for Koskisen

floor chipboard.

# 12.2 Walls

The link below is to installation instructions for Koskisen wall boards.

# **13. Usage instructions**

# 13.1 Machining

The chipboard can be sawn, drilled and cut using any conventional woodworking tools. Blades become duller somewhat more quickly than when machining wood. For that reason, when machining larger board amounts, carbide-tipped blades are recommended. The best machining results is obtained with well sharpened tools and high cutting speeds.

Chipboard may also be bought ready-machined, for example with tongue and groove. Figure 3 presents common tongue and groove models:

# 13.2 Gluing properties

Chipboard has good gluing properties. In general, the same resins can be used as in wood. Low-water, dense resins are recommended. The resin may not be thinned with water.

# 13.3 Surface coating

Chipboard may be painted, wallpapered, veneered or covered with other surface coatings. The dense, homogeneous surface of chipboard forms an even basis for paint and thin surface coatings. Chipboard may be painted with all paints intended for wood surface treatment. Thinning of paint with water should be avoided. To achieve a high-quality paint surface, the boards should first be painted with a primer, or a board to which primer or a painting film has been applied at the factory should be used.

# 13.4 Storage, processing and transport

Boards are protected during transport and storage from moisture, dirt, ground contact, chipping and scratching. Boards are stored face down on a level surface. If necessary, bearers 0.5 m apart are used. The board stack is covered with a protective board.

Chipboard should be air conditioned for 5 to 7 days before installation in humidity and temperature conditions that are close as possible to the intended conditions.

# 13.5 Disposal

If the boards are intact and dry, they may be used again on discretion on a case-by-case basis. Reuse is the most recommended way to "dispose" of chipboard. As chipboard chiefly consists of pure natural timber, it can be disposed of (in compliance with local environmental instructions) by composting, landfill disposal or burning at over 800°C with other wood.

**[KoskiFloor installation instructions](https://koskisen.fi/wp-content/uploads/2021/09/87877.pdf)** 

**[KoskiFloor Tandem installation instructions](https://koskisen.fi/wp-content/uploads/2021/09/87887.pdf)** 

**[KoskiWall installation instructions](https://koskisen.fi/wp-content/uploads/2021/09/87945.pdf)** 

Figure 3. Common tongue and groove models.

**Chipboard standard T&G**



**Wall board T&G** Thicknesses 11–12 mm

**T&G (standard)** Thicknesses 16–30 mm Most common floor thicknesses 18, 22 and 25 mm.

**DTG (double T&G, "tandem")** Thicknesses 22–25 mm Double tongue enables seams between the framing.

**FTG (symmetrical straight T&G)** Thicknesses 30–40 mm

**HL (half tongue)** Thicknesses 8–40 mm







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# **14. Chipboard environmental considerations**

Chipboard makes use of the by-products of sawmilling and plywood industry, and it consists of 90% wood. Chipboard is thus a carbon store: the carbon contained in the timber is retained in the board as long as the board is used and until it is disposed of, such as by incineration for energy. Chipboard binds wood carbon for much longer than other wood products such as cardboard and paper.

An average carbon footprint has been calculated for coated melamine chipboard and uncoated chipboard. The carbon contained in chipboard compensates emissions and the chipboard serves as a carbon sink. The carbon footprint calculations are available on the Koskisen website.

# **Sources**

[PROPERTIES](#page-3-0) [STRENGTH GRADES](#page-4-0) STRENGTH GRADES [SPECIAL PRODUCTS](#page-5-0)

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### **[EPD KoskiPan](https://koskisen.fi/wp-content/uploads/2021/11/EPD-KoskiPan-1.pdf)**

TABLES





Laadusta tekijä tunnetaan.

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